

Operation:SMT+DIP 3.1 Type-C 连接器 / 24PIN 卧式



LTEM NO.:MC-312D-C

(L7.90mm×W8.94mm×H3.20mm CONNECTORS)



Technical parameter

PROJECT	LEVEL	A[better product]	B[average product]
	Contact Rating	5.0A, 12V DC	
Electrical Properties	Initial Contact Resistance	30mΩ max.	50mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Skey/PD: 100MΩ min.300V DC
	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut
Durable Performance	There No Load	10,000 Cycles	8,000 Cycles
	Rated Load	8,500 Cycles	6,500 Cycles
	Storage temp.	-35℃~+75℃(Operating Temp:)	

表面 SMT+DIP

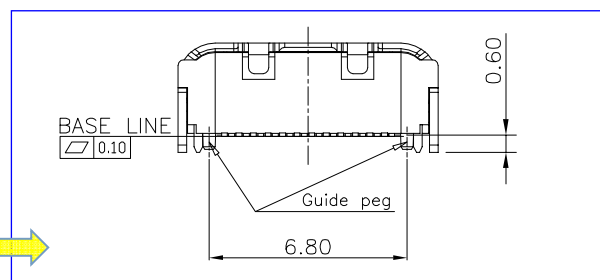
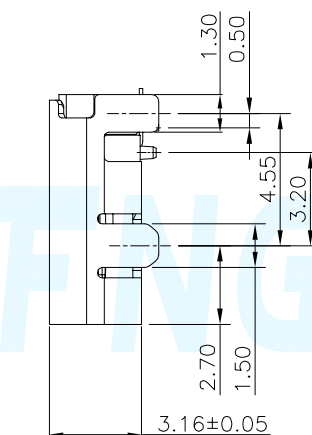
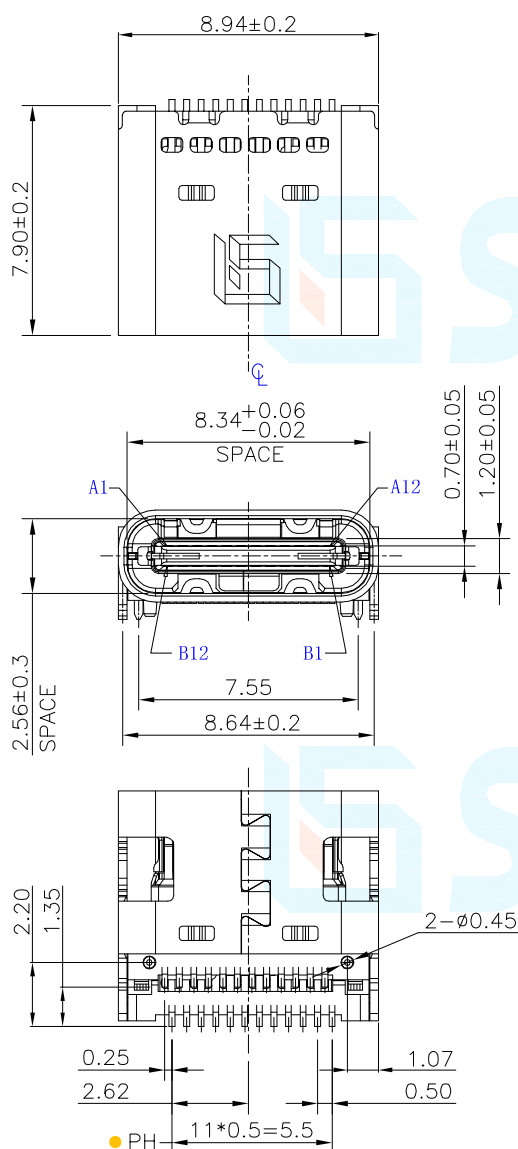
側向導入 LATERAL

精密部品 NICETY

可靠 STABILIZE

適合環保 RoHS

Unit:mm



Material declaration

No.	NAME	MATERIAL	DESCRIPTION
① A	TERMINAL 接触端子	COPPER ALLOY 【G/F】	2.0 μ m Ni PLATED OVERALL; 0.25 μ m Au PLATED CONTACT AREA; GOLD FLASH ON SOLDER AREA.
② B	HOUSING 基座	THERMOPLASTIC	UL 94V-0,COLOR:BLACK;
③ C	SHIELDING PLATE 屏蔽壳	STAINLESS STEE	【G/F】 0.25 μ m Ni PLATED OVERALL;
④ D	SHELL 外壳	STAINLESS STEE	【G/F】 0.25 μ m Ni PLATED OVERALL;
⑤ E	GND RING 接地件	STAINLESS STEE	STAINLESS STEEL;

Operating Force

Inward

5.0~8.0N. (1N.=100gram-force)

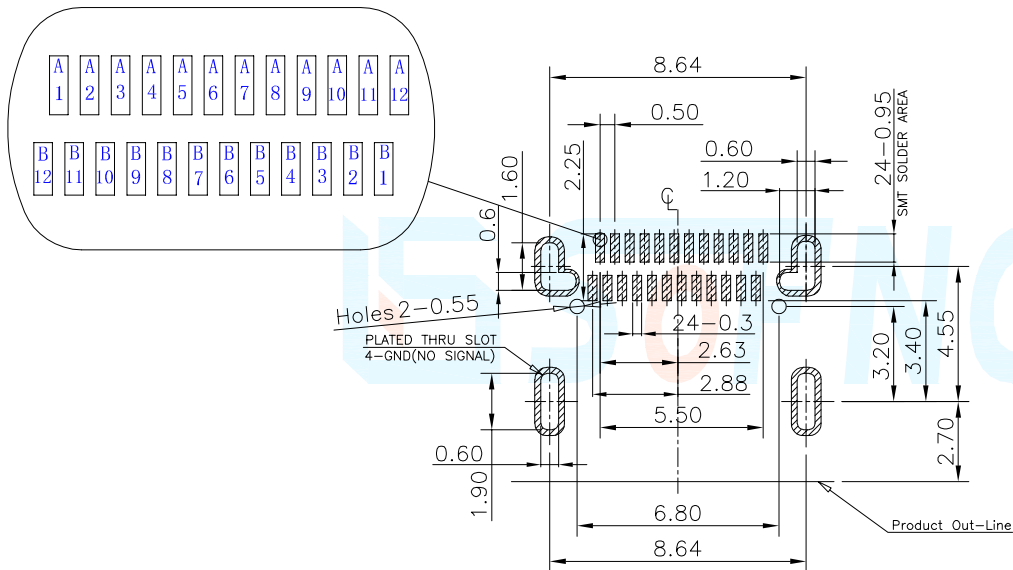
Exiting

5.0~8.0N. (1N.=100gram-force)

Solder-ability (Max.)

IR Reflow: 255°C, 5sec.

Manual: 350°C, 3sec.

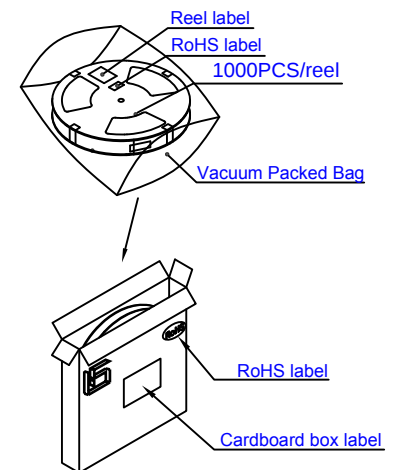


DECIMALS	ANGLES
.X :±0.25	X.° :±1.5°
.XX :±0.15	XX.° :±1.0°
.XXX :±0.10	XXX.° :±0.5°

Pin Definition



PIN	Signal NAME	Description	PIN	Signal NAME	Description
A 1	GND	Ground return	B12	GND	Ground return
A 2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A 3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A 4	V BUS	Bus Power	B 9	V BUS	Bus Power
A 5	CC1	Configuration Channel	B 8	SBU2	Sideband Use (SBU)
A 6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B 7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A 7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B 6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A 8	SBU1	Sideband Use (SBU)	B 5	CC2	Configuration Channel
A 9	V BUS	Bus Power	B 4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B 3	SSTXn2	Negative half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B 2	SSTXp2	Positive half of first SuperSpeed TX differential pair2
A12	GND	Ground return	B 1	GND	Ground return



本品不屬於危害性廢棄物,須丟棄時可以委託
回收商予以回收再生處理。
Products do not belong to •

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